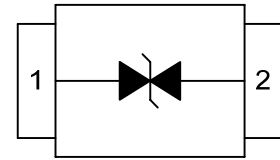


Description

The SBD52 series of Transient Voltage Suppressors (TVS) are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computer, and PDAs. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).



Pin Configuration

Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- Protects bi-directional line
- Peak power dissipation of 150W under 8/20 μ s waveform
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270 $^{\circ}$ C

Applications

- Cellular handsets & Accessories
- Cordless phones
- Personal digital assistants (PDAs)
- Notebooks & Handhelds
- Portable instrumentation
- Digital cameras
- Peripherals
- MP3 players

Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse power (tp=8/20 μ s waveform)	P _{PP}	150	W
ESD voltage (Contact discharge)	V _{ESD}	± 8	kV
ESD voltage (Air discharge)		± 15	
Storage & operating temperature range	T _{STG} , T _J	-55~+150	$^{\circ}$ C

Electrical Characteristics (T_J=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V _{RWM}				5	V
Reverse breakdown voltage	V _{BR}	I _{BR} =1mA	5.6		8	V
Reverse leakage current	I _R	V _R =5V			5	μA
Clamping voltage (t _p =8/20μs)	V _C	I _{PP} =1A			9.8	V
Off state junction capacitance	C _J	0Vdc, f=1MHz		30		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

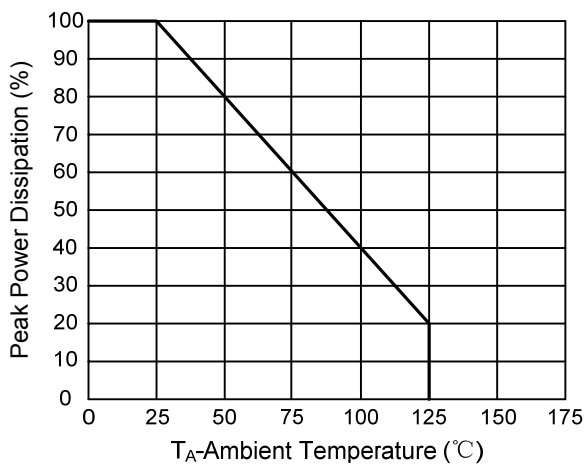


Figure 2. Pulse Waveforms

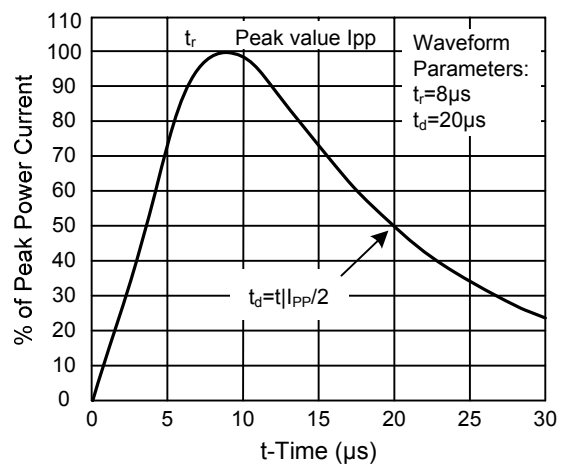


Figure 3. Clamping Voltage vs. Peak Pulse Current

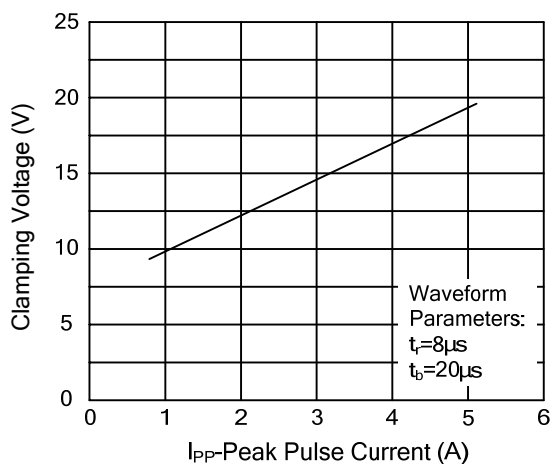
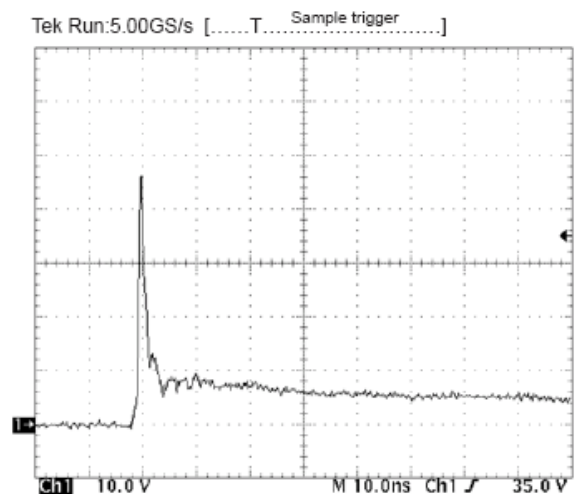
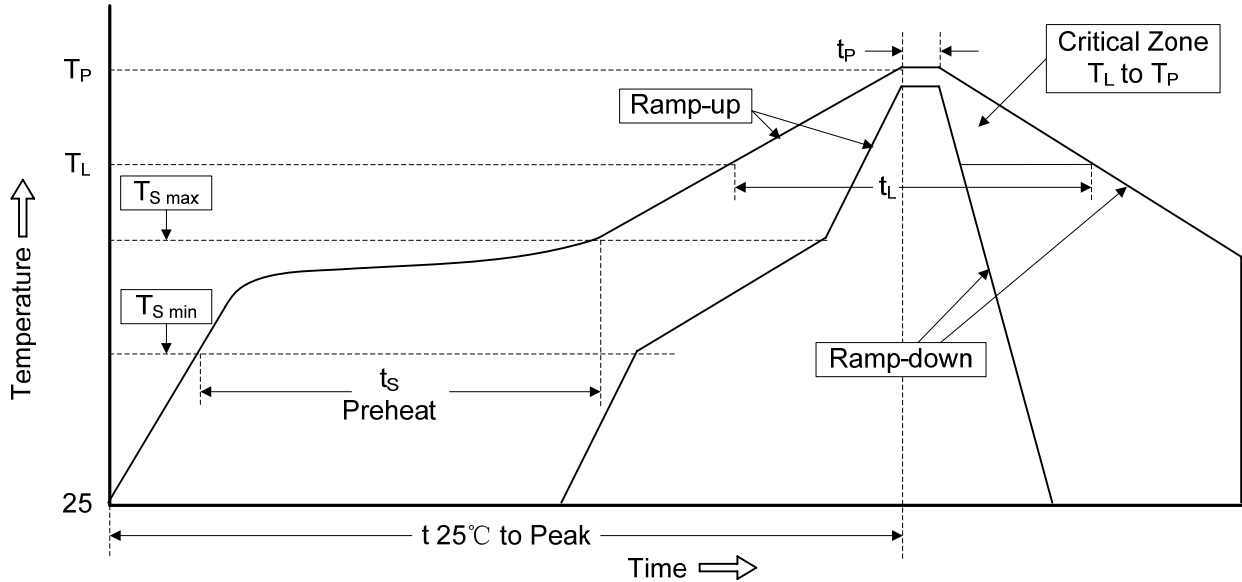


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

Reflow Soldering

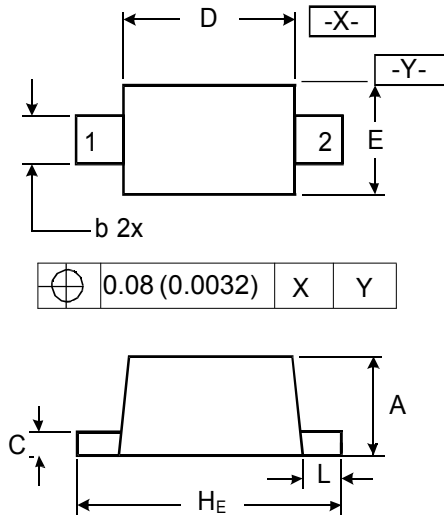


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Package outline dimensions

SOD-523



DIMENSIONS

SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.50	0.70	0.020	0.028
b	0.25	0.35	0.010	0.014
C	0.07	0.20	0.0028	0.0079
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
HE	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

Marking



Ordering information

Order code	Package	Base qty	Delivery mode
UMW SBD52C05L01	SOD-523	3000	Tape and reel

单击下面可查看定价，库存，交付和生命周期等信息

[>>UMW\(友台半导体\)](#)